

FABRICATION PARAMETERS:

THICKNESS: SILKSCREEN: SOLDERMASK: BOTH

1 OZ (EXT) /1 OZ (INT) COPPER WEIGHT

DESIGN TYPE: 0.009/0.005 MIN TRACE/GAP: LAYER COUNT: 6 LAYERS

NOTES: UNLESS OTHERWISE SPECIFIED

ALL MATERIALS, INCLUDING BUT NOT LIMITED TO BASE LAMINATE, BONDING MATERIALS 1. MATERIAL:

AND SOLDERMASK COATINGS FORMING THE FINISHED PRINTED CIRCUIT BOARD SHALL MEET UL-796 REQUIREMENTS AND BE ROHS COMPLIANT AND HAVE A FLAMMABILITY OF UL94V-O.

PLASTIC SHEET, LAMINATED METAL CLAD, TWO SIDES, BASE MATERIAL NEMA TYPE FR-4

GLASS EPOXY RESIN, COPPER-CLAD IN ACCORDANCE WITH 6 LAYER STACK-UP. COMPLIANT WITH LEAD FREE PROCESS.

SOLDERMASK OVER BARE COPPER (SMOBC) USING LIQUID PHOTO-IMAGEABLE SOLDERMASK IN 3. SOLDERMASK:

ACCORDANCE WITH IPC-SM-840.

4. PLATING:

5, FINISH:

HOLES REQUIRING PLATING, SEE HOLE CHART, TO HAVE 1 OZ. (0.0014) MIN. THK MIN. THICK COPPER

PLATE WITH ROHS COMPLIANT, IMMERSION SILVER PREFERRED, IMMERSION TIN OR Sn/Ag/Cu,

WITH RMA FLUX, 0.0005" +/- 0.0003" THICK MIN ALL EXPOSED AREAS

AS COATED, NO ACTIVE FLUXES ARE ACCEPTABLE.

6. LEGEND: IF REQUIRED, SILKSCREEN LEGEND(S) WITH WHITE NON-CONDUCTIVE EPOXY INK. 7. MARKINGS: BOARD MUST BEAR VENDOR'S IDENTIFICATION CODE (ETCH OR WHITE NON-CONDUCTIVE INK).

LOCATION OPTIONAL.

PC BOARD SHALL BE MANUFACTURED PER IPC-A-600 CLASS 2 REQUIREMENTS OR BETTER. 8. WORKMANSHIP:

9. DOCUMENTATION: PCB VENDOR IS REQUIRED TO RETURN ANY AND ALL DOCUMENTS SUPPLIED OR ULTIMATELY PURCHASED BY TEXAS

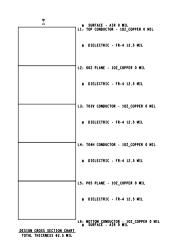
INSTRUMENTS UPON COMPLETION OF PURCHASE ORDER.

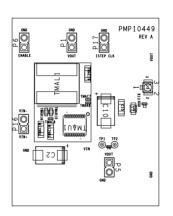
10. DRILL SIZES: HOLE DIAMETERS SHOWN ARE FINISHED SIZES AFTER PLATING UNLESS OTHERWISE NOTED.

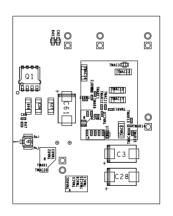
11. PANEL BORDER: ANY METAL IN BORDER AREA INCLUDING PART NUMBER, DATECODE AND/OR REVISION LETTERS MUST BE COVERED WITH SOLDERMASK.

12. PROCESS CHANGES:NO DIMENSIONAL, MATERIAL, OR PROCESS CHANGES ARE ALLOWED WITHOUT PRIOR EXPLICIT WRITTEN PERMISSION FROM TEXAS INSTRUMENTS.

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
· ·	10.0	+2.0/-7.0	PLATED	2
8	10.0	+3.0/-3.0	PLATED	57
A	20.0	+3.0/-3.0	PLATED	100
*	50.0	+3.0/-3.0	PLATED	10







ART FILM - assy2

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